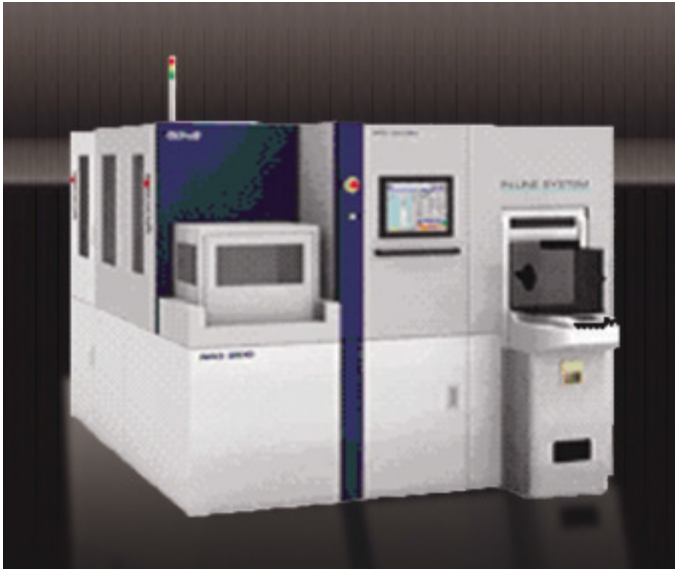


300mm Fully-Automatic Multifunction Wafer Mounter

RAD-2510F/12S_a



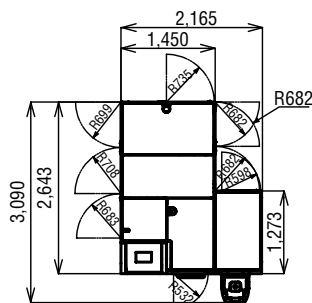
Outline

- Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions:
 - UV irradiation to BG Tape
 - Alignment
 - Wafer mounting
 - BG Tape peeling
- Ability to operate in-line with DISCO Corporation's DFG8000 series back grinder or DGP8000 series grinder/polisher.
- Corresponds to DBG process.
- Prevents wafer damage by reducing wafer handling frequency down to 4 times "stand-alone," and 2 times "in-line."

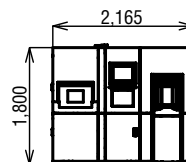
- Options**
- Host Communication Function (Communication Format : Conforms to SECS-I and HSMS/Software : Conforms to GEM)
 - Vision System (Wafer ID Reader & Barcode Attachment System)
 - Dicing Tape In-line Pre-cutting
 - DBG Process Compatibility
 - In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series

- Suitable Tapes**
- Dicing tape : Adwill D series, G series
 - Dicing die bonding tape : Adwill LE Tape

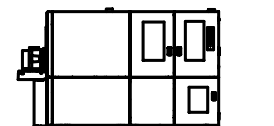
External View



Top View



Front View



Right Side View

Unit:mm

Facility

Power Supply	Voltage	: AC200 (±10%)
	Frequency	: 50/60Hz
	Phase	: 3 phase
	Power consumption	: 8.0kW (200VAC)
Air Supply	Air pressure	: 0.6-0.8MPa
	Air consumption	: >800L/min (ANR)
Vacuum Supply	Vacuum pressure	: >-80kPa

Applicable Wafer Size 200mm, 300mm

Size Width : 2,165mm
Depth : 3,090mm
Height : 1,800mm
(excluding the signal tower and protruding parts)

Weight 3,100kg

UPH 45wafers/hour

The above processing capacity is based on following conditions ("stand-alone"):

- Wafer : 300mm diameter non-polished mirror wafer
- Ring frame : for 300mm wafer
- Dicing tape : G-18 from LINTEC
- Back grinding tape : E-8180HR from LINTEC



LINTEC Corporation Linking your dreams

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<https://www.adwill-global.com/en>